



Spec No.: DS30-2011-0114Effective Date: 12/01/2011

Revision: -

LITE-ON DCC

RELEASE

BNS-OD-FC001/A4

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| LED DISPI | A T 7 |
|------------------------|--------------|
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LTS-4817CTB-P DATA SHEET

| <u>ITEM</u> | <u>Description</u> | By | DATE |
|-------------|---|-----------|------------|
| 1 | New Spec | Eason Lin | 2010/09/23 |
| 2 | 2.1 Modify packing dimensions.2.2 Modify recommended soldering condition patterns. | Reo Lin | 2011/09/21 |
| | | | |
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FEATURES

- *0.39 inch (10.0 mm) DIGIT HEIGHT
- *CONTINUOUS UNIFORM SEGMENTS
- ***LOW POWER REQUIREMENT**
- *EXCELLENT CHARACTERS APPEARANCE
- *HIGH BRIGHTNESS & HIGH CONTRAST
- *WIDE VIEWING ANGLE
- *** SOLID STATE RELIABILITY**
- *CATEGORIZED FOR LUMINOUS INTENSITY
- *SMD DISPLAY
- *LEAD FREE PACKAGE (ACCORDING TO ROHS)

DESCRIPTION

The LTS-4817CTB-P is a 0.39 inch (10.0 mm) digit height single digit SMD display. This device uses InGaN blue LED chips (InGaN epi on Sapphire substrate). The display has gray face and white segments, and suitable for reverse mount assembly.

DEVICE

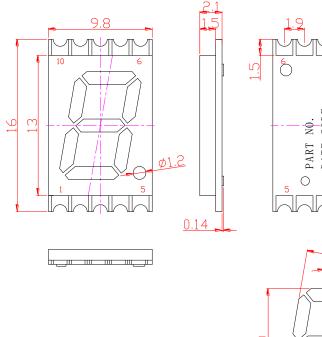
| PART NO. | DESCRIPTION |
|---------------|--------------|
| InGaN Blue | C |
| LTS-4817CTB-P | Common Anode |

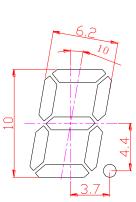
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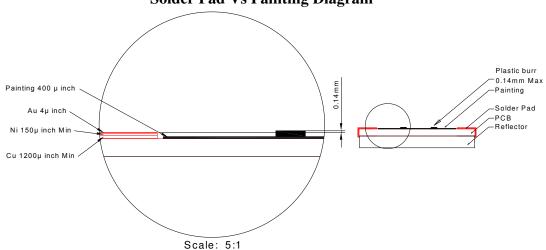
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PACKAGE DIMENSIONS





Solder Pad Vs Painting Diagram

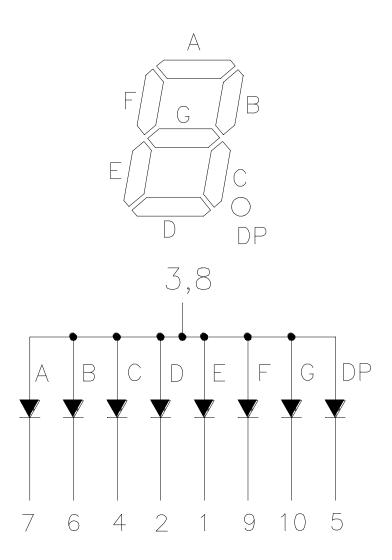


NOTES:

- 1. Plastic pins' burr max. 0.14 mm,
- 2. All dimensions are in millimeters. Tolerances are \pm 0.25mm (0.01") unless otherwise noted.
- 3. Solder pad materials and thickness: Cu: 1200μ inch Ni: Min 150μ inch Au: 4μ inch.

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INTERNAL CIRCUIT DIAGRAM



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PIN CONNECTION

| No. | CONNECTION |
|-----|--------------|
| 1 | CATHODE E |
| 2 | CATHODE D |
| 3 | COMMON ANODE |
| 4 | CATHODE C |
| 5 | CATHODE D.P. |
| 6 | CATHODE B |
| 7 | CATHODE A |
| 8 | COMMON ANODE |
| 9 | CATHODE F |
| 10 | CATHODE G |

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ABSOLUTE MAXIMUM RATING AT Ta = 25°C

| PARAMETER | MAXIMUM RATING | UNIT | |
|---|-------------------------------------|-------|--|
| Power Dissipation Per Segment | 70 | mW | |
| Peak Forward Current Per Segment | 100 | | |
| (Frequency 1Khz,10% duty cycle) | 100 | mA | |
| Continuous Forward Current Per Segment | 20 | mA | |
| Forward Current Derating from 25 °C | 0.21 | mA/°C | |
| Operating Temperature Range | -40° C to $+105^{\circ}$ C | | |
| Storage Temperature Range -40°C to +105°C | | | |
| Iron Soldering Conditions: 1/16 inch Below Seating Plane for 3 Seconds at 260°C | | | |

ELECTRICAL / OPTICAL CHARACTERISTICS AT Ta = 25°C

| PARAMETER | SYMBOL | MIN. | TYP. | MAX. | UNIT | TEST CONDITION |
|--|------------------|------|------|------|------|----------------------|
| Average Luminous Intensity | Iv | 8.4 | 26.8 | | mcd | $I_F = 10 \text{mA}$ |
| Peak Emission Wavelength | λр | | 468 | | nm | I _F =20mA |
| Spectral Line Half-Width | Δλ | | 25 | | nm | I _F =20mA |
| Dominant Wavelength | λd | | 470 | | nm | I _F =20mA |
| Forward Voltage Per Segment | V_{F} | | 3.3 | 3.6 | V | I _F =20mA |
| Reverse Current Per Segment ⁽²⁾ | Ir | | | 100 | uA | V _R =5V |
| Luminous Intensity Matching Ratio | Iv-m | | | 2:1 | | I _F =10mA |

Note:

- 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE (Commission Internationale De L'Eclairage) eye-response curve.
- 2. Reverse voltage is only for IR test. It can not continue to operate at this situation.

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| | | | |

TYPICAL ELECTRICAL / OPTICAL CHARACTERISTIC CURVES

(25°C Ambient Temperature Unless Otherwise Noted)

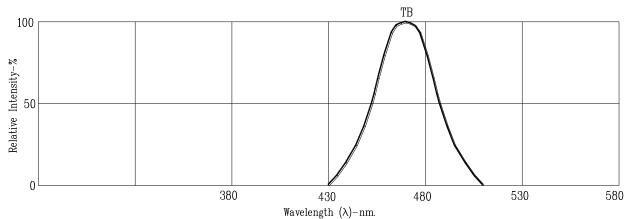
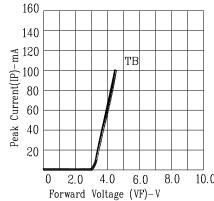


Fig1. RELATIVE INTENSITY VS. WAVELENGTH



FORWARD CURRENT FORWARD VOLTAGE

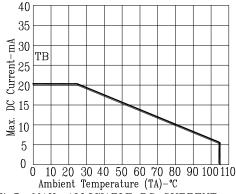
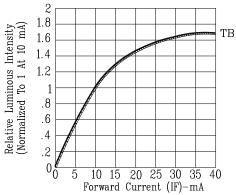
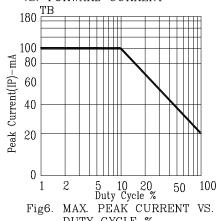


Fig5. MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATURE.



RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT



DUTY CYCLE % (REFRESH RATE 1KHz)

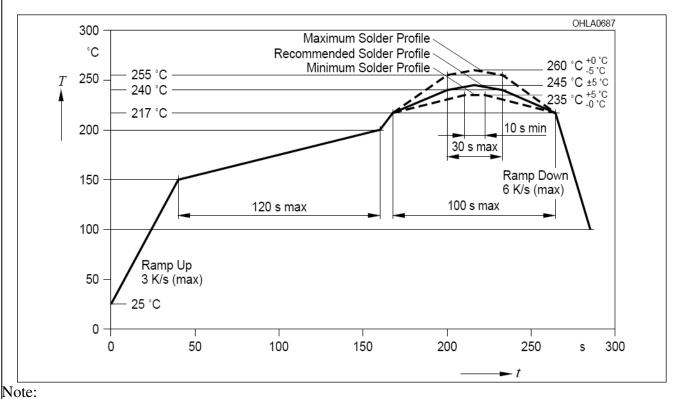
NOTE: TB=InGaN/sapphire Blue

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SMT SOLDERING INSTRUCTION



1. Recommended soldering condition:

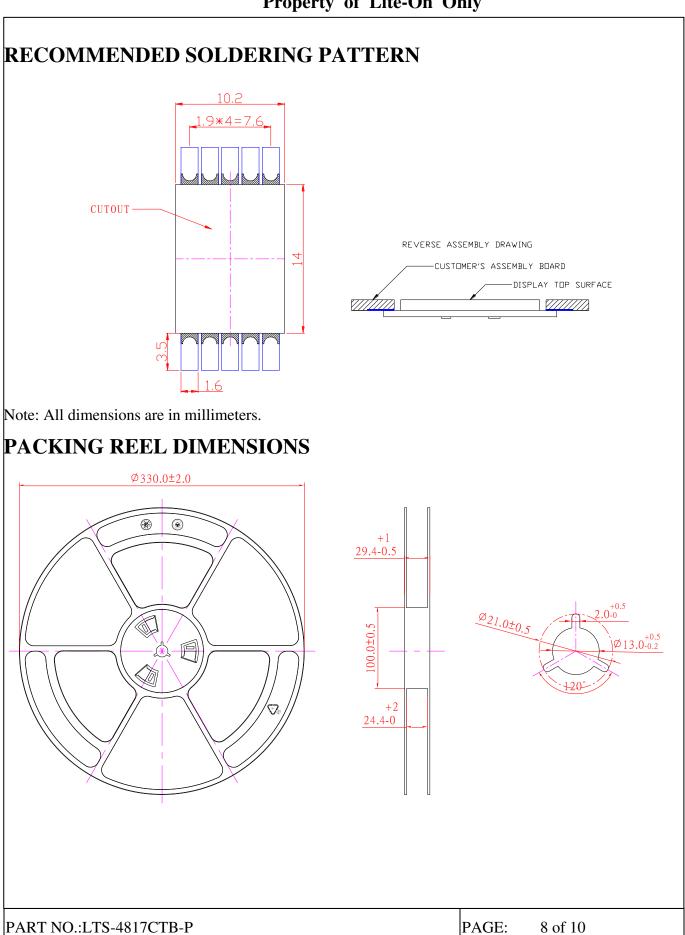
| Reflow Soldering (Two times only) | | Soldering Iron (One time only) | | |
|-----------------------------------|--------------|--------------------------------|------------|--|
| Pre-heat: | 120~150°C. | Temperature | 300°C Max. | |
| Pre-heat time: | 120sec. Max. | Soldering time | 3sec. Max. | |
| Peak temperature: | 260°C Max. | | | |
| Soldering time: | 5sec. Max. | | | |

2. Number of reflow process shall be less than 2 times, and cooling process to normal temperature is required between the first and the second soldering process.

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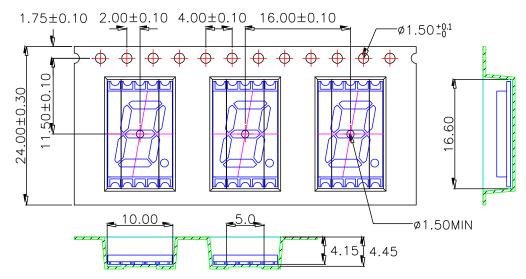


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PACKING CARRIER DIMENSIONS

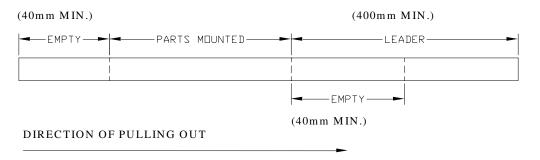
1. Taping parts:



- 1. 10 sprocket hole pitch cumulative tolerance ±0.20.
- Carrier camber is within 1 mm in 250 mm.
 All dimensions meet EIA-481-C requirements.
- 4. Thickness : 0.40±0.05mm.
- 5. Packing length per 22" reel: 45.50 Meters.
- 6. Component load per 13" reel: 800 pcs.

| W | 24.00±0.30 |
|-----|------------|
| A 0 | 10.00±0.10 |
| A 1 | 9.80±0.10 |
| В0 | 16.60±0.10 |
| B1 | 16.45±0.10 |
| K0 | 4.45±0.10 |
| K 1 | 4.15±0.10 |

2. Trailer part/ Leader part:



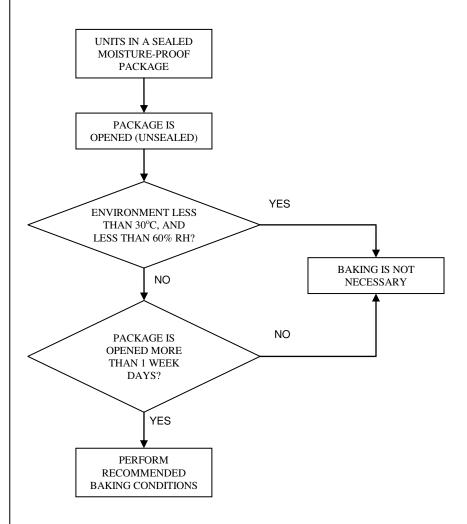
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Moisture Proof Packaging

All N/D SMD displays are shipped in moisture proof package. The displays should be stored at 30°C or less and 90% RH or less. Once the package opened, moisture absorption begins.



Baking Conditions

If the parts are not stored in dry conditions, they must be baked before reflow to prevent damage to the parts.

| Package | Temperature | Time |
|---------|-------------|----------|
| In Reel | 60°C | ≥48hours |
| In Bulk | 100°C | ≥4hours |
| | 125°C | ≧2hours |

Baking should only be done once.

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